

WS890 Water-Soluble Lead-Free Solder Paste

Introduction

WS890 solder paste is an excellent all-around water-soluble lead-free solder paste. WS890 has superior wetting, very low solder balling and graping. WS890 has been formulated for environmental stability giving long stencil life and excellent print characteristics. When coupled with SN100CV or LF-C2 alloys, WS890 provides a high reliability solution for harsh environments.

Attributes

- Superior reflow characteristics.
- Environmentally stable - long stencil life.
- Excellent print characteristics.

Solder Alloy	Solder Powder Size Availability (IPC J-STD-005)	Melting Range (°C)
SAC305	Type 3 or 4	217 - 220
SN100C	Type 3 or 4	227
SN100CV (Sn/Cu/Ni/Bi)	Type 3 or 4	221 - 225
Sn/Ag 3.5%	Type 3	221
LF-C2	Type 3 or 4	205 - 213
Anti-tombstoning mixtures	Type 3 or 4	Range depends on the mixture

- Other sizes of solder powder are available upon request.
- The size range for the solder powder types are as follows:
 - Type 3 (25-45 μm >80%). Mesh -325/+500
 - Type 4 (20-38 μm >80%). Mesh -400/+635
 - Type 5 (15-25 μm >80%). Mesh -500/+800

Solder Paste Packaging	Net Weight (grams)
Jars	250, 500
Cartridges	500 or 600 (6 oz), 700 (8 oz), 1300 (12 oz)
Syringes	30, 100
Enclosed print systems	800

Compatible Products

150N, 152N, 159HF liquid fluxes.
WS890 gel flux.

Storage and Handling

Best practices for storage and handling of solder paste are listed below. Additional details can be found in the Solder paste storage and handling guide.

- Shelf life is 9 months when stored at 0 to 10 °C (32 to 50 °F).
- Warm the solder paste to room temperature (18 to 29 °C / 65 to 85 °F) before use. Do not force warming by heating the solder paste. Keep the solder paste sealed while warming, which typically takes 3 to 4 hours at room temperature. Warming overnight is acceptable.
- Ideally solder paste should be mixed before use to bring it to a normal working consistency. This can be done by hand-stirring in a jar, or using a knead cycle on the printer.
- Best practice is to keep the solder paste at room temperature until completely used. Remaining fresh solder paste should be sealed in the original container along with all inserts, lids, etc.
- If solder paste is removed from the printer and stored, it is recommended to store it in a separate container from the fresh solder paste. The container should be sealed with all inserts, lids, etc.
- Once solder paste is applied to the circuit board, the best practice is to reflow the solder paste as soon as possible. It is acceptable to reflow within approximately 8 hours.

Print Parameter	Preferred	Acceptable
Solder paste bead size	1.5 to 2.0 cm (0.60 to 0.80 in)	1.0 to 2.5 cm (0.40 to 1.0 in)
Squeegee blade	Fine grain stainless steel. 60° from horizontal. 45° from horizontal for pin in paste.	Any type of stainless steel
Stencils	Fine grain (2-5 µm) or ultra-fine grain (1-2 µm) stainless steel	All types of commercially available stencils
Print speed	30 to 100 mm/sec (1.2 to 4.0 in/sec)	20 to 200 mm/sec (0.8 to 8.0 in/sec)
Pressure / blade length (increase with increasing speed)	0.27 to 0.36 kg/cm (1.5 to 2.0 lbs/in)	0.27 to 0.54 kg/cm (1.5 to 3.0 lbs/in)
Separation speed	1.0 to 5.0 mm/sec	0.5 to 10.0 mm/sec
Underside stencil cleaning	Wet / vacuum / vacuum cycle every 1-5 prints	Other cleaning cycles every 1 to 20 prints depending upon technology
Stencil life	8 hours at 18-29 °C (65-85 °F) and 10-70% RH.	Stencil life may be shorter outside of the preferred conditions.

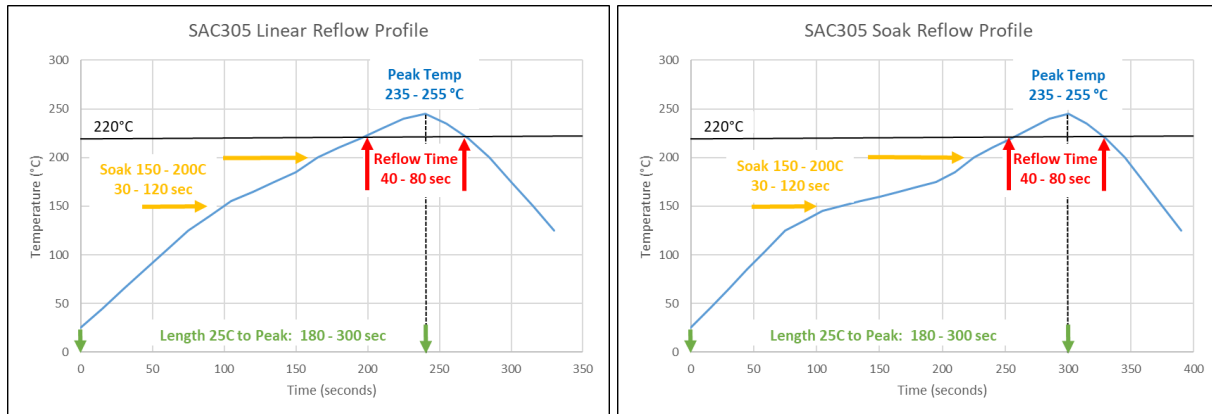
- Blade pressure should be set as low as possible to clean off the stencil. Higher blade pressures will increase stencil and blade wear, and can lead to “scooping” and other print defects.
- Underside stencil cleaning is best accomplished with commercial cleaners and high quality wipe materials. Nano-coated stencils can be used to reduce the frequency of underside cleaning.

Reflow Parameter	Preferred	Acceptable
Profile length (25 °C to peak)	3.5 to 4.5 min (210 to 270 sec)	3.0 to 5.0 min (180 to 300 sec)
Heating ramp rate (20 second window)	1.0 to 2.0 °C/sec	1.0 to 3.0 °C/sec
Preheat / soak time (150 - 200 °C)	60 to 90 sec	30 to 120 sec
Peak temperature	240 to 250 °C for SAC alloys 245 to 255 °C for SN100C	235 to 255 °C for SAC alloys 240 to 260 °C for SN100C

Reflow time (time above liquidus)	50 to 70 sec	40 to 80 sec
Cooling ramp rate (20 second window)	3.0 to 6.0 °C/sec	1.0 to 6.0 °C/sec

- Reflow time should be calculated based on the liquidus point of the alloy used: SN100C = 227°C, SN100CV = 225°C, SAC305 = 220°C, Sn96.5/Ag3.5 = 221°C, LF-C2 = 213°C.

Example reflow profile graphs are shown below. These are a good starting point but they can be modified to fit the product and process. Contact FCT Assembly for assistance with reflow profiling.



Cleaning

Raw solder paste can be removed from the stencil, squeegee blades, and circuit boards using a variety of commercial cleaners. Isopropyl alcohol (IPA) can also be used.

WS890 flux residues are corrosive and must be removed using a suitable wash process. It is recommended to remove WS890 flux residues within 4 hours after soldering using D.I. water heated to 100 - 180 °F in standard washing equipment. It is possible to wash away WS890 flux residues after multiple heat cycles followed by a 24 hour hold time, although this is not recommended.

Safety

Wear chemically resistant gloves when handling solder paste. Avoid breathing fumes, especially during reflow of the solder paste. Follow the guidelines detailed in the Safety Data Sheet (SDS).

J-STD-004B Flux Standard	Test Method	Result
J-STD-004B classification	J-STD-004B methods	ORH1
Halide ion content (Br ⁻ , Cl ⁻ , F ⁻ , I ⁻)	IPC 2.3.28.1	1.7 to 1.8% wt of solids
Halogen content (Br and Cl)	EN 14582, IPC 2.3.28.1	6.8 to 7.2% wt of solids
Halide by silver chromate	IPC 2.3.33	Halides detected
Fluoride by spot test	IPC 2.3.35.1	None detected
Copper mirror	IPC 2.3.32	High activity
Copper corrosion	IPC 2.6.15	Corrosion present

Surface Insulation Resistance (SIR)	IPC 2.6.3.7	Pass > 1.00E+08 ohms
Electro Chemical Migration (ECM)	IPC 2.6.14.1	Pass, increase of 1.5 Log ₁₀ ohms
J-STD-005 Solder Paste Standard	Test Method	Result
Viscosity - Brookfield	IPC 2.4.34	Refer to the C of A
Slump - frosted glass	IPC 2.4.35	Pass
Solder balling - frosted glass	IPC 2.4.43	Preferred
Wetting - copper	IPC 2.4.45	Pass

Limited Liability and Warranty Disclaimer

All information, statements, technical data, and recommendations contained in this Technical Data Sheet are based on testing we believe to be reliable. However, the accuracy or completeness thereof is not guaranteed. It is impossible for our lab to account for all manufacturing conditions and variables. Products are warranted to be free from defects at the time sold. To the full extent consistent with applicable law, the exclusive remedy of the user or buyer is to receive replacement product for any product defective at the time sold. FCT Assembly, Inc. makes NO WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE. Further, FCT Assembly, Inc. makes no other express, implied, or statutory warranties unless otherwise specified in writing and signed by officers of the corporation.